# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs  
**Marketing Name / Model**  
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Notebook, HP Notebook 11</th>
</tr>
</thead>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.  
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, WLAN</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries  Battery cell &amp; RTC</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove base rubber foot -L & -R
2. Remove screw rubber foot -L & -R
3. Dis-fasten BASE screw*11
4. Pull out FFC*3 (Power, Touchpad, keyboard membrane)
5. Dis-fasten battery screw *4
6. Remove battery
7. Pull out wire cable *4 (LCD, DC, SPEAKER, WLAN) Pull out FFC (DB)
8. Dis-fasten daughter boards screw *2 (DB, WLAN)
9. Remove daughter boards*2 (DB, WLAN)
10. Dis-fasten speaker -L & -R screw*2
11. Remove speaker -L & -R
12. Remove HDD
13. Dis-fasten motherboard screw *4
14. Remove motherboard
15. Dis-fasten daughter boards screw*4 (Power, Touchpad)
16. Remove daughter boards*2 (Power, Touchpad )
17. Dis-fasten KB Hook screw*1
18. Remove KB Hook
19. Dis-fasten HEAT SINK screw*4
20. Remove HEAT SINK
21. Dis-fasten Hinge screw*4
22. Remove Screw MYLAR -L & -R
23. Dis-fasten LCD Bezel screws*2
24. Remove LCD bezel
25. Dis-fasten Hinge screw*4
26. Pull out LCD cable & camera cable
27. Remove LCD module
28. Remove Camera module
29. Remove LCD cable & camera cable
30. Dis-fasten Hinge screw*6
31. Remove Hinge -L & -R
32. Remove Antenna cables

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total

PSG instructions for this template are available at EL-MF877-01
3.22 Remove base rubber foot -L & -R and screw rubber foot -L & -R

3.23 Remove TOP assy..

PSG instructions for this template are available at EL-MF877-01
3.24 Remove Power boards & Touchpad & KB Hook & HEAT SINK

PSG instructions for this template are available at EL-MF877-01
3.25 Remove battery, HDD & daughter boards*2 (DB, WLAN)

3.26 Remove speaker -L & -R, DC-in cable & motherboard

PSG instructions for this template are available at EL-MF877-01
3.27 Remove Screw Mylar -L & -R and LCD bezel

3.28 Remove Panel

3.29 Remove Camera module and Hinge -L & -R & LCD cable

3.30 Remove Antenna cables

PSG instructions for this template are available at EL-MF877-01